



Material Content Data Sheet



Sales Product Name		TLE8366EV		Issued		27. September 2017		
MA#		MA000971490						
Package		PG-DSO-8-27		Weight*		84.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.728	3.24	3.24	32351	32351
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.728	0.86		8630	
wire	non noble metal	copper	7440-50-8	29.548	35.04	35.95	350412	359581
	noble metal	gold	7440-57-5	0.283	0.34	0.34	3356	3356
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1155	
	plastics	epoxy resin	-	4.481	5.31		53143	
	inorganic material	silicondioxide	60676-86-0	44.130	52.34	57.77	523344	577642
leadfinish	non noble metal	tin	7440-31-5	0.704	0.83	0.83	8347	8347
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8592	8592
glue	plastics	epoxy resin	-	0.214	0.25		2533	
	noble metal	silver	7440-22-4	0.641	0.76	1.01	7598	10131
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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